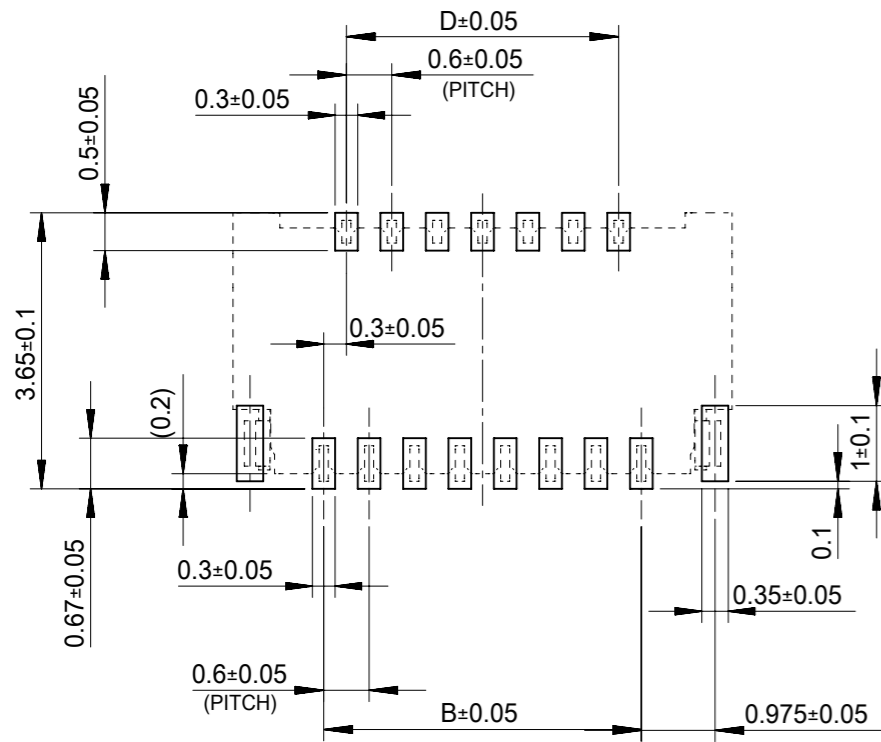


注記 NOTES:  
 1.材質 MATERIAL  
 ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)  
 GLASS FILLED, UL94V-0  
 アクチュエータ: ポリアミド樹脂  
 黒色、ガラス充填、UL94HB  
 ACTUATOR: POLYAMIDE  
 BLACK GLASS FILLED, UL94HB  
 ターミナル: 燐青銅 (t=0.12)  
 TERMINAL: PHOSPHOR BRONZE (t=0.12)  
 金具: 燐青銅 (t=0.15)  
 NAIL: PHOSPHOR BRONZE (t=0.15)  
 2.めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部: 金めっき 0.1μm以上  
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM  
 半田付け部: 金めっき  
 SOLDER TAIL AREA: GOLD  
 下地めっき: ニッケル 1.0μm以上  
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
 金具 NAIL  
 錫めっき 1.0μm以上  
 TIN PLATING 1.0 MICROMETER MINIMUM  
 下地めっき: ニッケル 1.0μm以上  
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
 3.平坦度は、0.1ミリ以下とする。  
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.  
 4.ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT  
 5.本製品は502598-\*\*91の端子材料変更品である。  
 THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*91.

14.4	16.95	15	17.4	502598-5193	51
12.6	15.15	13.2	15.6	502598-4593	45
11.4	13.95	12.0	14.4	502598-4193	41
10.8	13.35	11.4	13.8	502598-3993	39
9	11.55	9.6	12	502598-3393	33
7.8	10.35	8.4	10.8	502598-2993	29
7.2	9.75	7.8	10.2	502598-2793	27
6.6	9.15	7.2	9.6	502598-2593	25
6	8.55	6.6	9	502598-2393	23
4.2	6.75	4.8	7.2	502598-1793	17
3.6	6.15	4.2	6.6	502598-1593	15
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-\*\*21

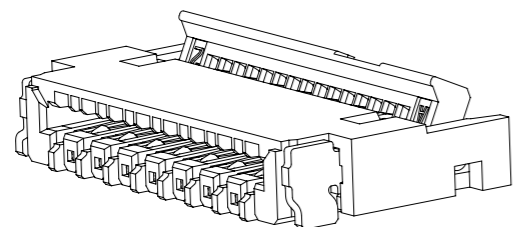
GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE mm NTS		CURRENT REV DESC:			
10 UNDER 未満	±0.2	4 PLACES	±	EC NO: 704374	2022/04/25		
10 OVER 以上	±0.25	3 PLACES	±	DRWN: KYHWANG	2022/05/09	PRODUCT CUSTOMER DRAWING	
30 UNDER 未満	±0.25	2 PLACES	±	CHK'D: SMARUYAMA	2022/05/09	DOCUMENT NUMBER	
30 OVER 以上	±0.3	1 PLACE	±	APPR: YNAITO	2022/05/09	SD-502598-003	
ANGLE 角度	±1°	0 PLACES	±	INITIAL REVISION:		DOC TYPE DOC PART REVISION	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRWN: KMIYAHARA	2012/07/18	PSD 001 C	
				APPR: KMORIKAWA	2012/08/01	SHEET NUMBER	
				DRAWING	A3-SIZE	1 OF 2	
				SERIES	502598	GENERAL MARKET	
				MATERIAL NUMBER	SEE TABLE		
				CUSTOMER	GENERAL MARKET		



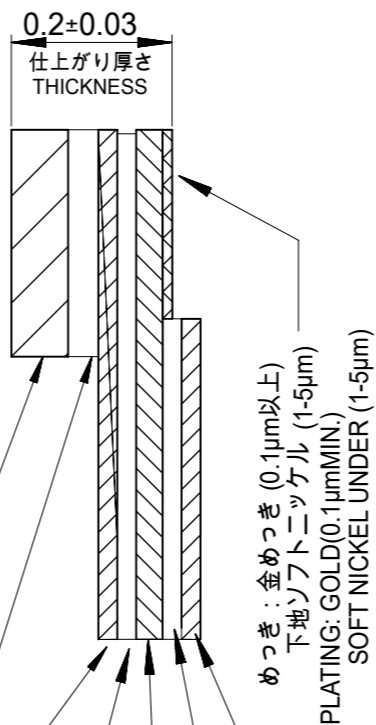
推奨基板寸法

RECOMMENDED P.W.B. PATTERN LAYOUT

マスク厚 : 100 $\mu$ m  
 マスク開口率 : 100%  
 SCREEN THICKNESS : 100 $\mu$ m  
 SCREEN OPEN RATIO : 100%



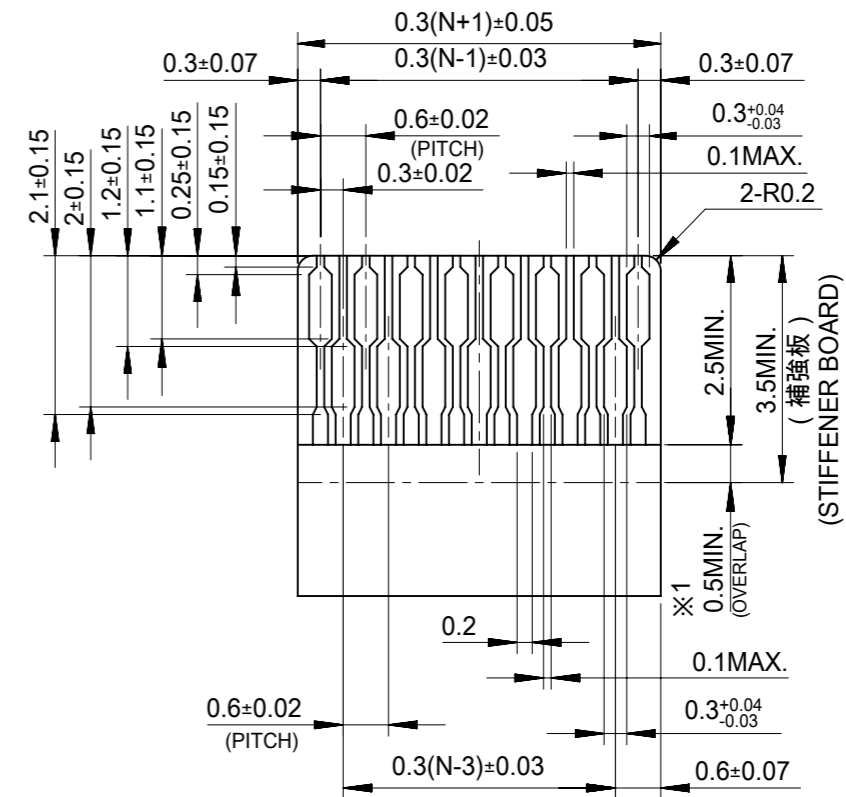
ISO VIEW (参考)



補強板 : ポリイミド  
 REINFORCE BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム : ポリイミド (25 $\mu$ m)  
 BASE FILM: POLYIMIDE(25 $\mu$ m)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 導体部 : 銅箔 (35 $\mu$ m)  
 COPPER FOIL (35 $\mu$ m)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバーレイ : ポリイミド (25 $\mu$ m)  
 COVER FILM: POLYIMIDE(25 $\mu$ m)

FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD PATING  
 RECOMMENDED DIMENSION

(仕上がり厚さ : 0.2 $\pm$ 0.03)  
 (THICKNESS:0.2 $\pm$ 0.03)

N : 極数  
 N:CIRCUITS

FPCについて :

抜き方向は、導体側から補強板側を推奨致します。  
 補強フィルム材質は、ポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、  
 染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN  
 ELECTRICAL CONTINUITY.

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE
		mm NTS
10 UNDER 未満	$\pm 0.2$	ANGULAR TOL $\pm$ °
10 OVER 以上	30 UNDER 未満 $\pm 0.25$	4 PLACES $\pm$
30 OVER 以上	$\pm 0.3$	3 PLACES $\pm$
ANGLE 角度	$\pm 1^\circ$	2 PLACES $\pm$
		1 PLACE $\pm$
		0 PLACES $\pm$

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS: mm SCALE: NTS

CURRENT REV DESC:

EC NO: 704374  
 DRWN: KYHWANG 2022/04/25  
 CHK'D: SMARUYAMA 2022/05/09  
 APPR: YNAITO 2022/05/09

INITIAL REVISION:  
 DRWN: KMIYAHARA 2012/07/18  
 APPR: KMORIKAWA 2012/08/01

THIRD ANGLE PROJECTION

DRAWING: A3-SIZE SERIES: 502598

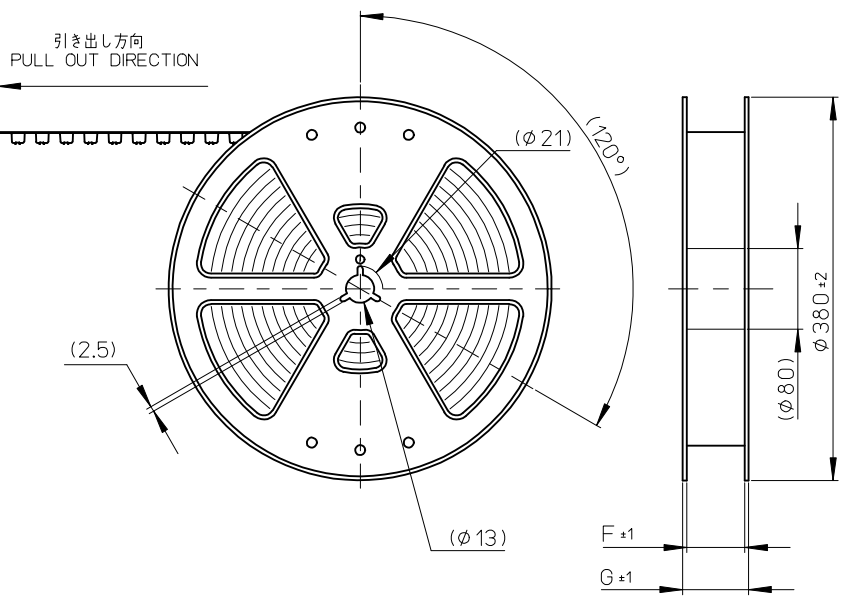
MATERIAL NUMBER: SEE SHEET 1 CUSTOMER: GENERAL MARKET SHEET NUMBER: 2 OF 2

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: SD-502598-003 DOC TYPE: PSD DOC PART: 001 REVISION: C

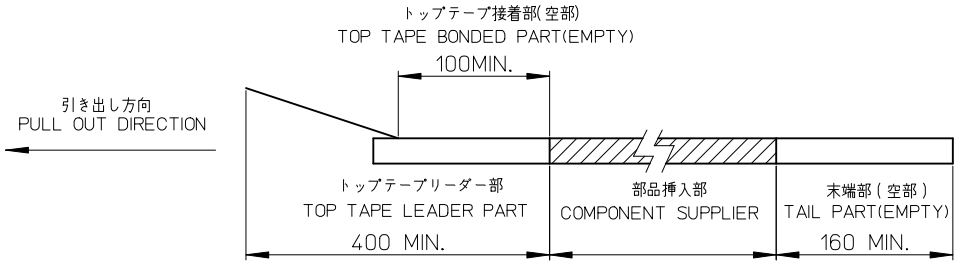
**molex**

0.3 FPC CONN. BACK FLIP HOUSING ASSY



注記)  
NOTES

1. 製品番号502598-\*\*-21の詳細寸法は、製品単体図面を参照下さい。  
IN THE PACKAGE PART NUMBER 502598-\*\*-21 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール  
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ  
LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料  
MATERIAL  
キャリアテープ: ポリスチレン (PS)  
CARRIER TAPE: POLYSTYRENE (PS)  
トップテープ: ポリエチレンテレフタラート (PET)、他  
TOP TAPE : POLYETHYLENE TELEPHTHALATE (PET), OTHERS  
リール: ポリスチレン (PS)  
REEL: POLYSTYRENE (PS)

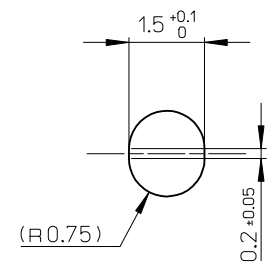
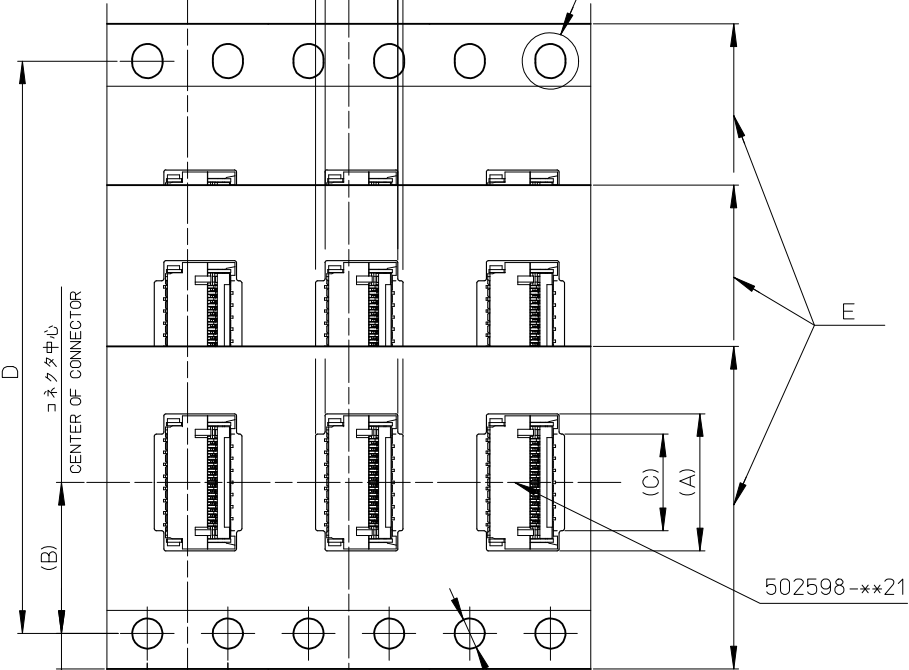
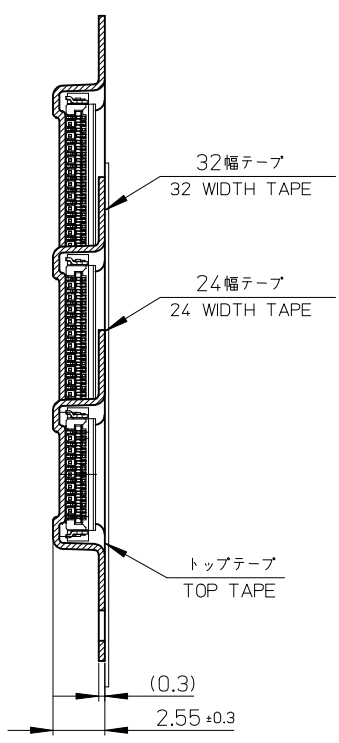
6. ELV及RoHS適合品  
ELV AND RoHS COMPLIANT
7. 本製品は502598-\*\*-91の端子材料変更品である。  
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*-91.

REVISED EC NO: J2014-0146 DRWN: KNAGUMO 2013/07/25 CHKD: KAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**-21 SERIES) <b>molex</b> DOCUMENT NO. SD-502598-004 SHEET NO. 1 OF 2		
	10 OVER 30 UNDER	± ---	CHECKED BY KAKAHASHI	DATE 2012/07/18			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2012/08/01			
ANGULAR ±1 °		MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

引き出し方向  
PULL OUT DIRECTION

Y  
8 ± 0.1  
(PITCH)  
(2.43)  
(4.34)  
(3.61)



T部詳細  
DETAIL T

断面 Y-Y  
SECTION Y-Y

1.75 ± 0.1

(B)

(2)

4 ± 0.1

累積ピッチ : 40 ± 0.2  
ACUUMLATIVE PITCH : 40 ± 0.2

37.4	33.4	32 ± 0.3	28.4	15.7	14.2	17.6	502598-5193	51
29.4	25.4	24 ± 0.3	--	13.9	11.5	15.8	502598-4593	45
				12.7		14.6	502598-4193	41
				12.1		14	502598-3993	39
				10.3		12.2	502598-3393	33
				9.1		11	502598-2993	29
				8.5		10.4	502598-2793	27
				7.9		9.8	502598-2593	25
21.4	17.4	16 ± 0.3	--	7.3	7.5	9.2	502598-2393	23
				5.5		7.4	502598-1793	17
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	4.9	7.5	6.8	502598-1593	15
				製品番号 MATERIAL NO.		極数 CIRCUITS		

REVISED EC NO: J2014-0146 DRWN: KAGUMO 2013/07/25 CHKD: TAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**21 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2012/08/01				
ANGULAR	± 1 °	MATERIAL NO.		DOCUMENT NO. SD-502598-004	SHEET NO. 2 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2